



Final Product Change Notification

201707002F01

Issue Date: 24-Aug-2017

Effective Date: 21-Nov-2017

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online



QUALITY

Change Category

| | | | | |
|--|---|--|---|---|
| <input type="checkbox"/> Wafer Fab Process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Test Location | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab Materials | <input type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Process | <input type="checkbox"/> Errata |
| <input checked="" type="checkbox"/> Wafer Fab Location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |

MCF5225X Fab Site Expansion (TSMC3 to NXP-CHD)

Details of this Change

NXP Semiconductors is announcing the qualification of the NXP Chandler, Arizona, USA (NXP-CHD) wafer fabrication facility as a dual source wafer manufacturing location for the MCF5225X.

The current mask set for product sourced out of TSMC3 Fab is identified as 1M42N.

The new mask set for product sourced out of NXP-CHD Fab is identified as 0N18K.

Why do we Implement this Change

The Fab manufacturing site capacity expansion to NXP-CHD will improve NXP's ability to meet increasing customer demand and maintain supply.

Identification of Affected Products

Top side marking

The mask set marking for product sourced out of TSMC3 Fab is 1M42N.

The mask set marking for product sourced out of NXP-CHD Fab is 0N18K.

Product Availability

Sample Information

Samples are available upon request

Samples PCF52255CAF80 from the 100LQFP package is available.

Production

Planned first shipment 07-Oct-2017

Impact

There is no change to product form, fit, function, or reliability.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Fab Expansion. No Depletion of Inventory required.

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 23-Sep-2017.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name cuizhe zhang
Position Product Engineer
e-mail address cuizhe.zhang@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

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| Changed Orderable Part# | Changed Part 12NC | Changed Part Number | Changed Part Description | Package Name | Status | Product Line |
|-------------------------|-------------------|---------------------|--------------------------|--------------|--------|---------------------|
| MCF52254CAF66 | 935322567557 | MCF52254CAF66 | KIRIN3 COLDFIRE V2 | LQFP100 | RFS | BL Microcontrollers |
| MCF52255CAF80 | 935309317557 | MCF52255CAF80 | KIRIN3 COLDFIRE V2 | LQFP100 | RFS | BL Microcontrollers |
| MCF52258CAG66 | 935314016557 | MCF52258CAG66 | KIRIN3 COLDFIRE V2 | LQFP144 | RFS | BL Microcontrollers |
| MCF52258AG80 | 935317009557 | MCF52258AG80 | KIRIN3 COLDFIRE V2 | LQFP144 | RFS | BL Microcontrollers |
| MCF52259CAG80 | 935309895557 | MCF52259CAG80 | KIRIN3 COLDFIRE V2 | LQFP144 | RFS | BL Microcontrollers |
| MCF52256CAG66 | 935321329557 | MCF52256CAG66 | KIRIN3 COLDFIRE V2 | LQFP144 | RFS | BL Microcontrollers |
| MCF52254AF80 | 935309316557 | MCF52254AF80 | KIRIN3 COLDFIRE V2 | LQFP100 | RFS | BL Microcontrollers |